

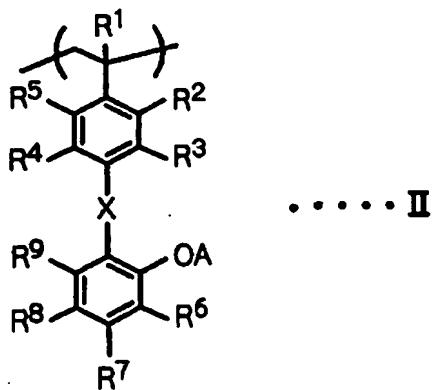
AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings of claims in the application:

LISTING OF CLAIMS:

1-15 cancelled

16. (new) A photosensitive resin composition comprising the styrene polymer and a photosensitizer, wherein the styrene polymer comprises one or more repeating constitutional units represented by general formula II:



wherein R¹ represents hydrogen atom or methyl group; R² to R⁹ independently represent hydrogen atom, halogen atom or alkyl group having 1 to 4 carbon atoms; X represents -CH=N-, -CONH-, -(CH₂)_n-CH=N- or -(CH₂)_n-CONH-, and the N atom in X is bonded to a carbon atom in the benzene ring having AO- at an o-position; A represents hydrogen atom or a group being decomposed by an acid; and n represents an integer of 1 to 3.

17. (new): A positive photosensitive resin composition using the photosensitive resin composition as claimed in Claim 16; wherein the styrene polymer has a constitutional unit represented by general formula II in which A is hydrogen atom; comprising a diazonaphthoquinonesulfonate derivative as the photosensitizer.

18. (new): A positive photosensitive resin composition using the photosensitive resin composition as claimed in Claim 16; wherein the styrene polymer has an acid decomposable group; comprising a photoacid generator as the photosensitizer.

19. (new): A negative photosensitive resin composition using the photosensitive resin composition as claimed in Claim 16; wherein the styrene polymer has an acid crosslinkable group; comprising a photoacid generator as the photosensitizer.

20. (new): The negative photosensitive resin composition as claimed in Claim 19, comprising a polyfunctional epoxy compound.

21. (new): The negative photosensitive resin composition as claimed in Claim 19, comprising a phenol derivative or a polynuclear phenol derivative.

22. (new): The negative photosensitive resin composition as claimed in Claim 19, comprising a polyol.

23. (new): A patterning method comprising at least: an application step applying the photosensitive resin composition of Claim 16 on a processed substrate; a pre-bake step fixing the photosensitive resin composition on the processed substrate; an exposure step selectively exposing the photosensitive resin composition; a development step dissolving and removing the exposed or the unexposed area in the photosensitive resin composition to form a pattern; and a post-bake step curing the patterned photosensitive resin composition.

24. (new): A patterning method comprising at least: an application step applying the positive photosensitive resin composition of Claim 16 on a processed substrate; a pre-bake step fixing the photosensitive resin composition on the processed substrate; an exposure step selectively exposing the photosensitive resin composition; a development step

dissolving and removing the exposed or the unexposed area in the photosensitive resin composition to form a pattern; and a post-bake step curing the patterned photosensitive resin composition.

25. (new): A patterning method comprising at least: an application step applying the positive photosensitive resin composition of Claim 18 on a processed substrate; a pre-bake step fixing the photosensitive resin composition on the processed substrate; an exposure step selectively exposing the photosensitive resin composition; a development step dissolving and removing the exposed or the unexposed area in the photosensitive resin composition to form a pattern; and a post-bake step curing the patterned photosensitive resin composition.

26. (new): The patterning method as claimed in Claim 25; further comprising a post-exposure-bake step diffusing a generated acid by the exposure between the exposure step and the development step; wherein the exposed area is dissolved and removed in the development step.

27. (new): The patterning method as claimed in Claim 26; further comprising a post-exposure step between the development step and the post-bake step.

28. A patterning method comprising at least: an application step applying the negative photosensitive resin composition of Claim 19 on a processed substrate; a pre-bake step fixing the photosensitive resin composition on the processed substrate; an exposure step selectively exposing the photosensitive resin composition; a development step dissolving and removing the exposed or the unexposed area in the photosensitive resin composition to form a pattern; and a post-bake step curing the patterned photosensitive resin composition.

29. (new): The patterning method as claimed in Claim 28; further comprising a post-exposure-bake step diffusing a

generated acid by the exposure between the exposure step and the development step; wherein the unexposed area is dissolved and removed in the development step.